



SILICON DIE CHIPPING IMPROVEMENT THROUGH FULL SANDWICH DOUBLE-SIDED WAFER MOUNTING TECHNIQUE



DOCTOR OF PHILOSOPHY

2025



Faculty of Mechanical Technology and Engineering

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SANDWICH DOUBLE-SIDED WAFER MOUNTING TECHNIQUE**

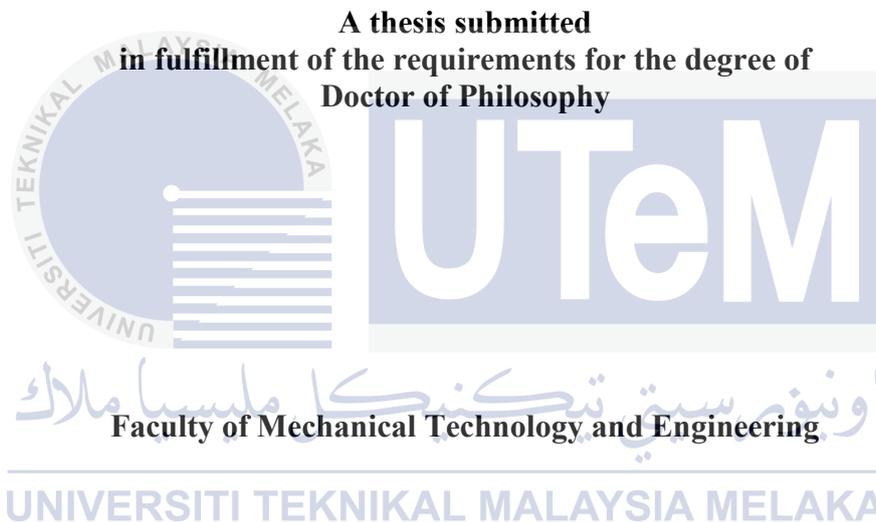
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UNIVERSITI TEKNIKAL MALAYSIA MELAKA

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DOUBLE-SIDED WAFER MOUNTING TECHNIQUE**

MOHD SYHRIN AMRI BIN MOHD NOH



UNIVERSITI TEKNIKAL MALAYSIA MELAKA

2025

DECLARATION

I declare that this thesis entitled “Silicon Die Chipping Improvement Through Full Sandwich Double-Sided Wafer Mounting Technique“ is the result of my own research except as cited in the references. The thesis has not been accepted for any degree and is not concurrently submitted in candidature of any other degree.



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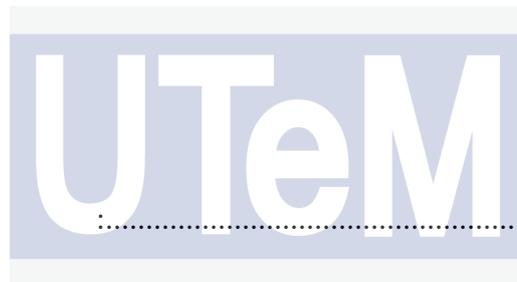
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APPROVAL

I hereby declare that I have read this thesis and in my opinion this thesis is sufficient in terms of scope and quality for the award of Doctor of Philosophy.



Signature



Supervisor Name : Prof. Ir. Ts. Dr. Ghazali bin Omar

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DEDICATION

"In The Name of Allah, The Most Gracious, The Most Merciful"

This thesis is dedicated to God Almighty, my originator, my source of inspiration, wisdom, knowledge, and comprehension, and my pillar of fortitude. To my wife, Halimah binti Sulaiman, who has been an unwavering source of encouragement and support. I am extremely grateful for your presence in my daily life. To my children, Nurul Fatihah, Muhammad Syahmi, Nurul Faqihah, and Nurul Firzanah, who have been significantly affected by this endeavour. This work is also dedicated to my parent, Mohd Noh Bin Abd Razak and Rohana Binti Chik, who have always loved me unconditionally and whose exemplary behaviour has inspired me to work assiduously towards my goals. I am extremely grateful. There is no way to quantify my love for each of you.

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ABSTRACT

This study investigates the development and evaluation of new wafer mounting techniques designed to enhance wafer holding capability, with the primary objective of minimizing chipping and improving the flexural strength of silicon dies by reducing vibration during the wafer dicing process. The conventional single-sided wafer mounting approach was found to be inadequate, particularly in stabilizing non-polished wafers with backgrinding marks, which resulted in insufficient tape adhesion, increased vibration, and compromised mechanical stability during dicing. Chipping was identified as the most critical defect, accounting for 15% of failures within the 23% defect rate related to wafer dicing processes. To address these limitations, double-sided semi-sandwich and full-sandwich wafer mounting configurations were developed and evaluated using UV Tape A, UV Tape B, and non-UV tape. A key focus of the study was the optimisation of UV curing parameters, particularly curing speed, to enable the automatic removal of surface UV mounting tape after dicing, ensuring a seamless transition to subsequent processing steps. Experimental findings showed that UV tape with an adhesive strength of 30 mN/25 mm achieved complete detachment when cured at an optimized speed of 10 mm/s. To assess the impact of this optimization, a comprehensive comparative analysis was performed between the conventional single-sided wafer mounting technique and the proposed double-sided configurations, namely the semi sandwich and full sandwich wafer mounting techniques. Comparative analysis revealed that the full sandwich configuration significantly outperformed the conventional single-sided method, achieving an 84% reduction in topside chipping, a 40% enhancement in die flexural strength, and a 26% reduction in vibration amplitude during dicing. These results validate the double-sided full sandwich wafer mounting technique as a novel and practical solution for improving wafer dicing performance in semiconductor manufacturing applications.

**PENINGKATAN ACUAN SERPIHAN SILIKON MELALUI TEKNIK PELEKATAN
WAFER TERAPIT SISI BERKEMBAR PENUH**

ABSTRAK

Kajian ini menyiasat pembangunan dan penilaian terhadap teknik pemasangan wafer baharu yang direka bentuk untuk meningkatkan keupayaan pegangan wafer, dengan objektif utama untuk meminimumkan kecacatan serpihan dan meningkatkan kekuatan lenturan acuan silikon melalui pengurangan getaran semasa proses pemotongan wafer. Kaedah pemasangan wafer satu sisi yang konvensional didapati tidak mencukupi, khususnya dalam menstabilkan wafer yang tidak digilap dan mempunyai kesan pencanaan belakang, yang mengakibatkan lekatan pita yang tidak memadai, peningkatan getaran, serta kestabilan mekanikal yang terganggu semasa proses pemotongan. Serpihan dikenal pasti sebagai kecacatan paling kritikal, yang menyumbang sebanyak 15% daripada jumlah kadar kecacatan 23% berkaitan dengan proses pemotongan wafer. Bagi menangani kekangan ini, konfigurasi teknik pelekatan wafer terapit sisi berkembar separuh dan penuh telah dibangunkan dan dinilai menggunakan Pita UV A, Pita UV B, serta pita bukan UV. Tumpuan utama kajian ini adalah pengoptimuman parameter penyinaran UV, terutamanya kelajuan penyinaran, untuk membolehkan penanggalan automatik pita pelekat UV bahagian permukaan selepas pemotongan, bagi memastikan kelancaran peralihan ke langkah pemprosesan seterusnya. Dapatan eksperimen menunjukkan bahawa pita UV dengan kekuatan lekatan 30 mN/25 mm berjaya ditanggalkan sepenuhnya apabila disinari pada kelajuan optimum 10 mm/s. Untuk menilai kesan pengoptimuman ini, satu analisis perbandingan menyeluruh telah dijalankan antara teknik pelekatan wafer satu sisi konvensional dan konfigurasi pelekatan wafer terapit sisi berkembar yang dicadangkan, iaitu teknik separuh dan penuh. Hasil analisis menunjukkan bahawa konfigurasi penuh sandwich menunjukkan prestasi jauh lebih baik berbanding kaedah sebelah tunggal konvensional, dengan pengurangan sebanyak 84% dalam serpihan permukaan atas, peningkatan 40% dalam kekuatan lenturan die, dan pengurangan 26% dalam amplitud getaran semasa proses pemotongan. Keputusan ini mengesahkan bahawa teknik pelekatan wafer terapit sisi penuh merupakan pendekatan baharu yang praktikal dan berkesan dalam meningkatkan prestasi pemotongan wafer dalam aplikasi pembuatan semikonduktor.

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TABLE OF CONTENTS

	PAGE
DECLARATION	
APPROVAL	
DEDICATION	
ABSTRACT	i
ABSTRAK	ii
ACKNOWLEDGMENTS	iii
TABLE OF CONTENTS	iv
LIST OF TABLES	vii
LIST OF FIGURES	viii
LIST OF APPENDICES	xiii
LIST OF ABBREVIATION	xiv
LIST OF SYMBOLS	xvi
LIST OF PUBLICATIONS	xvii
AWARDS AND SCHOLARSHIPS	xviii
CHAPTER	
1. INTRODUCTION	1
1.1 Background	1
1.2 Problem Statement	13
1.3 The Objectives of This Thesis	19
1.4 Scope of Work	19
1.5 Hypothesis/Research Questions	21
1.6 Thesis outline	22
2. LITERATURE REVIEW	24
2.1 Overview	24
2.2 High concern on excessive chipping causes crack die in semiconductor manufacturing	25
2.3 Process flow of IC manufacturing and potential stress area	29
2.3.1 Wafer Backgrinding	31
2.3.2 Wafer Mounting	40
2.3.3 Wafer Dicing	53
2.4 Current wafer singulation techniques in semiconductor industries	61
2.4.1 Dicing after grinding (Current method)	62
2.4.2 Dicing before grinding	71
2.4.3 Laser cut after grinding	72
2.4.4 Laser cut before grinding	73
2.4.5 Plasma dicing	74
2.4.6 Die strength analysis at wafer dicing process	76
2.4.7 Vibration analysis during wafer dicing process	77
2.4.8 Research gap	80
2.5 Summary	95

3.	RESEARCH METHODOLOGY	96
3.1	Overview	96
3.2	Flow Chart of the Research	97
3.3	Research materials	101
3.3.1	Wafer	101
3.3.2	Mounting tape	102
3.3.3	Dicing blade	105
3.4	Samples preparation	106
3.4.1	Wafer back grinding	107
3.5	Wafer mounting	108
3.6	Wafer dicing	113
3.7	Ultraviolet (UV) curing	115
3.8	Mounting tape peeling test using tensile strength machine	119
3.9	Sample performance monitoring	121
3.9.1	Wafer cleaning process	122
3.9.2	Manual surface peeling test	122
3.9.3	Chipping measurement	124
3.9.4	Crack inspection	127
3.9.5	Die backside topography measurement	127
3.9.6	Three-point bending test	128
3.9.7	Wafer dicing vibration analysis	132
3.10	Summary	134
4.	RESULTS AND DISCUSSIONS	136
4.1	Introduction	136
4.2	Developing a double-sided wafer mounting technique	136
4.2.1	Evaluating surface mounting tape removal through manual peeling test	138
4.2.1	Surface mounting tape removal through manual peeling test yield	139
4.2.2	Evaluating surface mounting tape removal through UV curing dosage optimization	145
4.2.3	Mounting techniques vs chipping performance	151
4.2.4	Die backside topography measurement	162
4.3	Three-point bending test	166
4.3.1	Test speed assessment	167
4.3.2	Three-point bending test on mounting techniques	168
4.4	Vibration analysis on mounting techniques	171
4.5	Summary	174
5.	CONCLUSION AND FUTURE WORK	176
5.1	Conclusion	176
5.2	Contribution to Research Work	179
5.3	Suggestions for Future Work	181
	REFERENCES	184

APPENDIX A	201
APPENDIX B	202
APPENDIX C	204
APPENDIX D	205
APPENDIX E	206
APPENDIX F	208



LIST OF TABLES

TABLE	TITLE	PAGE
Table 1.1	Available wafer material in semiconductor manufacturing including the advantages and disadvantages	9
Table 2.1	Comparison of DDAF, Non-UV Tape, and UV Tape	47
Table 2.2	Compilation of the researcher's activities to improve chipping and crack issues during the wafer dicing process..	65
Table 2.3	Summary of the research gap from the singulation process and idea for improvement	80
Table 2.4	Process gap for each conventional wafer singulation technique	81
Table 2.5	The advantages and disadvantages for the conventional backgrinding, wafer mounting and wafer dicing process.	91
Table 3.1	Evaluated mounting tape specifications	103
Table 3.2	Mounting techniques vs mounting tape arrangement	112
Table 3.3	Fixed wafer dicing parameter	115
Table 3.4	Initial UV curing parameter	117
Table 3.5	UV curing evaluation for surface mounting tape removal after washing	118
Table 4.1	Initial 15 mm/s UV curing irradiation speed surface mounting tape peeling test results	139
Table 4.2	Results of UV dosage evaluation on surface mounting tape removal based on UV Tape B	146

LIST OF FIGURES

FIGURE	TITLE	PAGE
Figure 1.1	Chipping definition	3
Figure 1.2	IC components in cars today (Source: Infineon Technologies)	4
Figure 1.3	Grinding marks at wafer backside	12
Figure 1.4	Pareto diagram of wafer dicing defects (Sumagpang Jr. et al., 2020)	15
Figure 1.5	90-degree chipping area (Luo and Wang, 2008)	16
Figure 2.1	Chipping formation (a) diamond blade contact with wafer (b) after the wafer dicing process (T.-J. Su et al., 2018)	24
Figure 2.2	Topside chipping (a) side view (b) top view causing hairline crack (Han, 2020)	27
Figure 2.3	Backside chipping (a) side view (b) top view causing hairline crack (Han, 2020)	28
Figure 2.4	Assembly IC manufacturing process flow (Source: Infineon)	30
Figure 2.5	Illustration of wafer backgrinding process (Y.Liu et al., 2022)	31
Figure 2.6	Lower slurry flow rate produced higher temperature which increase chipping risk (Deng et al., 2025)	37
Figure 2.7	Laminate tape function (a) Wafer breakage and crack during grinding (b) Taping on the wafer surface for grinding stress absorbant (Bryan Christian S. Bacquian, 2020)	38
Figure 2.8	Wafer mounting process materials	41
Figure 2.9	Non-UV Tape wafer mounting and wafer dicing process flow	42
Figure 2.10	UV Tape wafer mounting and wafer dicing process flow	44
Figure 2.11	Dicing Die Attach Film (DDAF) and wafer dicing process flow	46

Figure 2.12	All mounting tapes using the conventional single-sided mounting technique	49
Figure 2.13	Chipping results (a) Topside chipping (b) Backside chipping	50
Figure 2.14	Backside chipping length DOE results.	51
Figure 2.15	Single cut performance (a) reduction of remnants on single cut with no bake method (b) high remnant on single cut with baking method	52
Figure 2.16	Wafer dicing operation	54
Figure 2.17	Die chipping samples (Xue et al., 2021)	55
Figure 2.18	Illustration of blade exposure and kerf width	56
Figure 2.19	Blade RPM illustration	57
Figure 2.20	Feed speed illustration	59
Figure 2.21	Wafer singulation techniques in the semiconductor manufacturing	75
Figure 2.22	Illustration of cushioning effects on the wafer surface and extra gripping at the wafer backside for the wafer mounting techniques	79
Figure 2.23	Summary of research gap and novelty on the overall project	88
Figure 3.1	Double-sided wafer mounting techniques	96
Figure 3.2	Flow chart on research activities	100
Figure 3.3	Mirror wafer	102
Figure 3.4	Diamond dicing blade	105
Figure 3.5	Disco blade specification code	106
Figure 3.6	Grinding marks at wafer back surface	107
Figure 3.7	Lintec RAD-2500 wafer mounter machine	109
Figure 3.8	Wafer mounting techniques used in the research	111
Figure 3.9	Disco DFD6362 Fully Automatic Dicing Saw Machine	113
Figure 3.10	Illustration of single-cut process on single-sided conventional mounting	114

Figure 3.11	Illustration of single-cut process on double-sided semi and full sandwich mounting	114
Figure 3.12	Lintec RAD-2010 UV curing	116
Figure 3.13	Tensilon RTG-1210 UV mounting tape peeling tester	120
Figure 3.14	180-degree peeling test	121
Figure 3.15	Wafer cleaning process on mounting technique with UV mounting tape	122
Figure 3.16	Surface peeling test process steps	123
Figure 3.17	Microscope micrometer calibration ruler	124
Figure 3.18	Chipping measurement process flow	125
Figure 3.19	Chipping measurement (a) Topside area (b) Backside area	126
Figure 3.20	Three-point bend test equation definition	129
Figure 3.21	50N Shimadzu EZ-LX machine for three-point bending test	129
Figure 3.22	Camera for consistent die positioning on jig during three-point bending test	130
Figure 3.23	3-point bending test jig design specification	131
Figure 3.24	Final 3-point bending test jig design	132
Figure 3.25	Vibration analysis tools	133
Figure 3.26	Vibration analysis setup	133
Figure 4.1	Overview of data collections on achieving all objectives	137
Figure 4.2	Summary of surface mounting tape manual peeling results based on 15mm/s UV curing irradiation speed	141
Figure 4.3	Non UV Tape with 0% manual peeling results (a) low magnification (b) zoom area on the wafer surface	142
Figure 4.4	UV Tape A with 70% manual peeling results (a) low magnification (b) zoom area on the wafer surface	143
Figure 4.5	UV Tape B with 100% manual peeling results (a) low magnification (b) zoom area on the wafer surface	145

Figure 4.6	15 mm/sec UV irradiation speed results (a) wafer after UV curing (b) wafer after UV curing and cleaning process	147
Figure 4.7	10 mm/sec UV irradiation speed results (a) wafer after UV curing (b) wafer after UV curing and cleaning process	148
Figure 4.8	5 mm/sec UV irradiation speed results (a) wafer after UV curing (b) wafer after UV curing and cleaning process	149
Figure 4.9	Peeling test results on UV Tape A and UV Tape B	150
Figure 4.10	Manual peeling process (a) Place cellophane tape on surface mounting tape (b) Pull up the cellophane tape (c) surface mounting tape peels off	153
Figure 4.11	Illustration of the automatic peeling process	153
Figure 4.12	Topside chipping performance between single-sided and double- sided wafer mounting techniques	154
Figure 4.13	SEM image on the topside areas	157
Figure 4.14	Backside chipping performance between single-sided and double- sided wafer mounting techniques	158
Figure 4.15	Illustration of mounting techniques toward wafer cushioning and gripping performance	159
Figure 4.16	SEM image on backside areas	161
Figure 4.17	Grinding marks patterns (a) Parallel with chipping (b) Perpendicular with chipping	162
Figure 4.18	Arithmetical mean roughness value (Ra) illustration	163
Figure 4.19	High chipping area surface roughness with parallel grinding marks (a)Bottom view (b) Bottom topography view	163
Figure 4.20	High chipping area surface roughness with perpendicular grinding marks (a) Bottom view (b) Bottom topography view	164
Figure 4.21	T-Test results on parallel and perpendicular chipping towards grinding marks	165
Figure 4.22	Test speed assessment results	167

Figure 4.23	Flexural strength performance based on mounting technique with fixed 3mm/min test speed	169
Figure 4.24	Compilation of wafer dicing vibration data on mounting techniques	172
Figure 4.25	Wafer dicing vibration analysis on wafer mounting techniques	173
Figure 5.1	Single and double-sided wafer mounting techniques performance	178



LIST OF APPENDICES

APPENDIX	TITLE	PAGE
Appendix A	3-Point Bending Test Jig Drawing	201
Appendix B	Wafer mounting calibration report	202
Appendix C	Wafer Dicing Calibration Report	204
Appendix D	UV Curing Calibration Report	205
Appendix E	Universal Testing Machine Calibration Report	206
Appendix F	Tensilon RTG 1210 Calibration by equipment supplier	208



LIST OF ABBREVIATION

ABS	-	Anti-lock braking systems
AOI	-	Automated optical inspection
BE	-	Back End
BGA	-	Ball Grid Array
CZ	-	Czochralski
DAG	-	Dicing After Grinding
DAF	-	Die Attach Film
DDAF	-	Dicing Die Attach Film
DGB	-	Dicing Before Grinding
EOL	-	End of line
FE	-	Front End
FOL	-	Front of line
FVI	-	Final visual inspection
IC	-	Integrated Circuits
PMC	-	Post Mold Cure
PSA	-	Pressure-sensitive adhesive
RPM	-	Rotation per minute
Sdn Bhd	-	A private limited company
SEM	-	Scanning electron microscope
Si	-	Silicon
SiC	-	Silicon Carbide

- UPH - Unit Per Hour
UTeM - Universiti Teknikal Malaysia Melaka
UV - Ultra Violet



LIST OF SYMBOLS

- $\sigma_{3 \text{ point}}$ - 3-points bending test
- α - significant test probability
- Ra - arithmetical mean roughness value



LIST OF PUBLICATIONS

Journal Articles

Mohd Syahrin Amri, Ghazali Omar, Mohd Syafiq Mispan, Fuaida Harun, Zaleha Mustafa, 2024. Semiconductor Chipping Improvement via a Full Sandwich Wafer Mounting Technique. *Majlesi Journal of Electrical Engineering Vol. 18, No. 1, March 2024 Semiconductor*, 10(2), pp. 743-758. (Scopus)

Mohd Syahrin Amri, Ghazali Omar, Mohd Syafiq Mispan, Fuaida Harun, MNB. Othman, and N.A. Ngatiman, 2024, Wafer Dicing Vibration Investigation on Novel Wafer Mounting Techniques, *IEEE Transactions on Semiconductor Manufacturing*. pp. 1312–1319. (WoS)

Mohd Syahrin Amri, Ghazali Omar, Mohd Syafiq Mispan, Fuaida Harun, Abdul Halim Dahalan, 2024, IJIE The Effects of Novel Sandwich Wafer Mounting Technique on Silicon Wafer Chipping Performance, *International Journal of Integrated Engineering*, vol. 16, no. 9, pp. 314–325. (WoS)

AWARDS AND SCHOLARSHIPS

Awards:

2023

- 1) ON Semi special award – Novel full sandwich wafer mounting technique for chipping and flexural strength improvement, Innovation Showcase 2023, UTeM - 26 October 2023.
- 2) 3rd prize award – Novel full sandwich wafer mounting technique for chipping and flexural strength improvement, Innovation Showcase 2023, UTeM - 26 October 2023.

